

CLAIMS

1. A method for manufacturing a flat printed wiring board in which spaces between circuit patterns are filled with a resin, said method comprising:

laminating via a mold release film a plurality of sets of laminated bodies formed by superposing a semi-cured resin sheet on a printed wiring board with said circuit patterns formed thereon; placing the laminated plural sets of said laminated bodies interposed between a pair of smoothing plates and collectively pressing said laminated bodies in a reduced pressure atmosphere in order to cure said resin; and then polishing said cured resin covering said circuit patterns, thereby exposing said circuit patterns.

2. The method for manufacturing a printed wiring board according to claim 1, wherein said circuit patterns are formed on both sides of said printed wiring board.

3. The method for manufacturing a printed wiring board according to claim 1 or claim 2, wherein a metallic foil with a roughened surface facing said resin layer is superposed on said resin layer.

4. The method for manufacturing a printed wiring board according to claim 3, wherein said metallic foil is formed with a different kind of metal than the kind of metal used to form said circuit pattern.